

186

Mildly Activated Rosin Liquid Flux Pen[®]

For Lead-bearing and Lead-free alloys

Part No. 060720

Product Description

Kester 186 Flux Pen[®] is specifically designed for leaded and lead-free rework of conventional and surface mount circuit board assemblies. Kester 186 under MIL-F-14256, was QPL approved as Type RMA. Although the fluxing ability approaches that of Type RA flux, residues after soldering are non-corrosive and non-conductive. Kester 186 has been developed for use in critical applications where difficult assemblies are to be soldered, but process requirements stipulate use of Type RMA flux. Kester 186 possess high thermal stability for soldering multi-layer assemblies which require higher temperatures. Exposure to high preheat temperatures does not degrade solubility of the residue in normal cleaning solvents. There is no surface insulation resistance degradation caused by the flux residue. The use of a minimum of ionic activating agents and the inactive nature of the residue permits leaving the residue on circuit board assemblies for many applications. The flux residue is also moisture and fungus resistant.

Performance Characteristics:

- High thermal stability
- Improves soldering performance
- Eliminates the need and expense of cleaning
- Classified as ROL0 per J-STD-004

RoHS Compliance

This product meets the requirements of the RoHS (Restriction of Hazardous Substances) Directive, 2002/95/EC Article 4 for the stated banned substances.

Physical Properties

Specific Gravity: 0.879 ± 0.003

Antoine Paar DMA 35 @ 25°C

Percent Solids (typical): 36

Tested to J-STD-004, IPC-TM-650, Method 2.3.34

Acid Number (typical): 55.5 mg KOH/g of flux

Tested to J-STD-004, IPC-TM-650, Method 2.3.13

Reliability Properties

Copper Mirror Corrosion: Low

Tested to J-STD-004, IPC-TM-650, Method 2.3.32

Corrosion Test: Low

Tested to J-STD-004, IPC-TM-650, Method 2.6.15

Silver Chromate: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.33

Chloride and Bromides: 0.02%

Tested to J-STD-004, IPC-TM-650, Method 2.3.35

Fluorides by Spot Test: Pass

Tested to J-STD-004, IPC-TM-650, Method 2.3.35.1

SIR, IPC (typical): Pass

Tested to J-STD-004, IPC-TM-650, Method 2.6.3.3

	Blank	186
Day 1	5.0 × 10 ⁹ Ω	3.1 × 10 ⁹ Ω
Day 4	5.8 × 10 ⁹ Ω	4.9 × 10 ⁹ Ω
Day 7	6.3 × 10 ⁹ Ω	5.5 × 10 ⁹ Ω

Application Notes

Flux Application:

Kester 186 is applied to circuit boards via Flux Pen® for rework of printed wire assemblies.

Process Considerations:

Kester 186 should only be applied to areas that will be fully heated by the soldering iron or other reflow tool. Care should be taken to avoid flooding the assembly. The surface tension has been adjusted to help the flux form a thin film on the board surface allowing rapid solvent evaporation.

Cleaning:

Kester 186 flux residues are non-conductive, non-corrosive and do not require removal in most applications.

Storage and Shelf Life:

Kester 186 is flammable. Store away from sources of ignition. Shelf life is 2 years from date of manufacture when handled properly and held at 10-25°C (50-77°F).

Health & Safety:

This product, during handling or use, may be hazardous to health or the environment. Read the Material Safety Data Sheet and warning label before using this product.

World Headquarters: 800 W. Thorndale Avenue, Itasca, Illinois, 60143 USA

Phone: (+1) 847-297-1600 • **Email:** customerservice@kester.com • **Website:** www.kester.com

Asia Pacific Headquarters

500 Chai Chee Lane
Singapore 469024
(+65) 6449-1133
customerservice@kester.com.sg

European Headquarters

Zum Plom 5
08541 Neuensalz
Germany
(+49) 3741 4233-0
customerservice@kester-eu.com

Japanese Headquarters

20-11 Yokokawa 2-Chome
Sumida-Ku
Tokyo 130-0003 Japan
(+81) 3-3624-5351
jpsales@kester.com.sg

The data recommendations presented are based on tests, which we consider reliable. Because Kester has no control over the conditions of use, we disclaim any responsibility connected with the use of any of our products or the information presented. We advise that all chemical products be used only by or under the direction of technically qualified personnel who are aware of the potential hazards involved and the necessity for reasonable care in their handling. The technical information contained herein is consistent with the properties of this material but should not be used in the preparation of specifications as it is intended for reference only. For assistance in preparing specifications, please contact your local Kester office for details.

Rev: 04Jun07